

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chi-Ming CHEN</td> <td>12/02/2010</td> </tr> <tr> <td>Chung-Yi YU</td> <td>12/02/2010</td> </tr> <tr> <td>Chia-Shiung TSAI</td> <td>12/02/2010</td> </tr> <tr> <td>Ho-Yung David HWANG</td> <td>12/08/2010</td> </tr> </tbody> </table>		Name	Execution Date	Chi-Ming CHEN	12/02/2010	Chung-Yi YU	12/02/2010	Chia-Shiung TSAI	12/02/2010	Ho-Yung David HWANG	12/08/2010
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RECEIVING PARTY DATA											
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.										
Street Address:	No. 8, Li-Hsin Rd. 6, Science Based Industrial Park										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12959984</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12959984						
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CORRESPONDENCE DATA											
Fax Number:	(214)200-0853										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	972-739-8635										
Email:	saadia.cooks@haynesboone.com										
Correspondent Name:	David M. O'Dell										
Address Line 1:	HAYNES AND BOONE, LLP.										
Address Line 2:	2323 Victory Avenue, Suite 700										
Address Line 4:	Dallas, TEXAS 75219										
ATTORNEY DOCKET NUMBER:	24061.1662										
NAME OF SUBMITTER:	David M. O'Dell										
Total Attachments: 3											

OP \$40.00 12959984

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**PATENT
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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|---------------------|----|---|
| (1) | Chi-Ming Chen | of | 8F, No. 145, Wenhua Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C. |
| (2) | Chung-Yi Yu | of | 14F, No. 18, Alley 6, Lane 485, Sec. 1, Kuang-Fu Road
Hsin-Chu, Taiwan, R.O.C. |
| (3) | Chia-Shiung Tsai | of | No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road
Hsin-Chu, Taiwan, R.O.C. |
| (4) | Ho-Yung David Hwang | of | Floor 6, No. 13, Alley 19, Guang Hsin Road
Hsinchu, Taiwan, R.O.C. |

have invented certain improvements in

REDUCING WAFER DISTORTION THROUGH A LOW CTE LAYER

for which we have executed an application for Letters Patent of the United States of America, filed on 12-03-2010 and assigned application number 12/959,984; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional,

continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chi-Ming Chen

Residence Address: 8F, No. 145, Wenhua Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

✓
Dated: 2010, 12.02

✓ CHI MING
Inventor Signature

Inventor Name: Chung-Yi Yu

Residence Address: 14F, No. 18, Alley 6, Lane 485, Sec. 1, Kuang-Fu Road
Hsin-Chu, Taiwan, R.O.C.

✓
Dated: 2010, 12.02

✓ Chung-Yi Yu
Inventor Signature

Inventor Name: Chia-Shiung Tsai

Residence Address: No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road
Hsin-Chu, Taiwan, R.O.C.

✓
Dated: 2010, 12, 02

✓ Chia Shiung Tsai
Inventor Signature

Inventor Name: Ho-Yung David Hwang
Residence Address: Floor 6, No. 13, Alley 19, Guang Hsin Road
Hsinchu, Taiwan, R.O.C.

Dated: Yung David Hwang
11/18/2010

Yung David Hwang
Inventor Signature
